

# IMAPS-UK Technical Online Conference

## “Making Sense of Sensors”

12th November 2020

[Register Here](#)

IMAPS-UK Technical Conference



### Conference Highlights:

*Discover New Technologies*

*Insightful Presentations*

*Industry Updates*

*Opportunities to Learn & Share*

*Technical Presentations on*

*Assembly Processes, Sensor*

*Types, Graphene and 3D*

*Printing*

This Technical Online Conference, organised by IMAPS-UK, focuses on the packaging challenges presented by the many varied applications driving the growing use of Sensors in our world.

Touching on Technologies & Assembly Processes common to all areas of the Microelectronics community, “**Making Sense of Sensors**” will provide insights into numerous packaging techniques. Highlighting packaging technologies, developments and opportunities, this technical conference will provide a forum for learning and sharing within this fascinating field. Topics presented will cover a wide range of industries and applications demonstrating the diverse nature of this sector and the wide array of packaging techniques that are applied.

**Making Sense of Sensors** provides an opportunity to learn from leading **Industry Experts** as they share their experiences and developments in this rapidly growing industry.

#### Topics include:

- **Assembly Processes** – vacuum, hermetic and non-hermetic packaging of MEMS and MOEMS devices
- **Sensor Types** – imaging, flow, pressure, LIDAR and tactile sensors
- **Graphene** – sensors applied in structural performance monitoring
- **3D Printing** – how 3D printing technologies are making an impact in sensor manufacturing

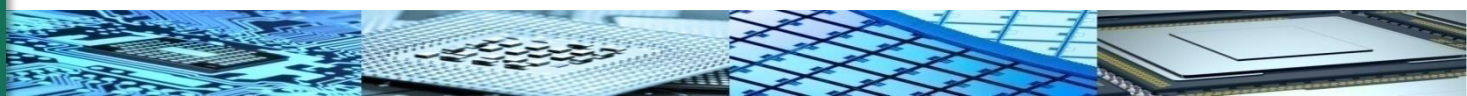
**Early booking is advised to avoid disappointment.**

### Registration Prices:

	<i>Delegates</i>
<i>IMAPS Member</i>	<i>FREE</i>
<i>IMAPS Student Member</i>	<i>FREE</i>
<i>Non Member</i>	<i>£50</i>

*Prices - £ exclude VAT, inclusive of online attendance and presentation downloads*

**“Where Industry Meets Online”**





### **Provisional Conference Agenda:**

10:00 **Welcome & Introduction**

#### **10:15 Session One: Packaging Challenges – Vacuum, Hermetic and Non-Hermetic Solutions**

- Vacuum Packaging of MEMS Systems – Ashwin Seshia, University of Cambridge
- Packaging of MOEMS LIDAR Sub-Assembly – Jonathan Abdilla, BESI
- Packaging of Sensors in Non-Hermetic Applications – John Boston, CIL UK

11:15 – 11:30 **Break**

#### **11:30 Session Two: Sensor Packaging Case Studies**

- Upgrade of Pressure Sensor Interface to High Temperature and CoB – Piers Tremlett, Microchip
- High Resolution 3D printing and self-powered tactile sensors – Manish Tiwari, UCL

12:30 **Lunch & Break**

#### **13:00 Session Three: Packaging Challenges – Flow Imaging and Graphene Sensors**

- Flow Sensor Package Design – Andrea de Luca, Flusso
- Imaging Sensor Development; From the Visible and Beyond – Ross Wheeler, Teledyne E2V
- Ultra-sensitive Graphene Sensors for Monitoring Performance and Structural Integrity in Power Electronics – Zlatka Stoeva, DZP Technologies

14:00 **Question and Answer Session**

14:30 **Closing Remarks & End**

### **Five reasons to attend:**

- It is “Where the Industry Meets Online”
- Access to leaders in the field
- Exposure to a range of Packaging Technologies
- Learn from Case Studies and Industry Trends.
- Discover new industry & business contacts

### **Access to Conference Presentations:**

Attendance at the conference includes post-conference downloadable access to the conference presentations including audio and visuals.

### **Sponsorship Opportunities:**

Please contact us if you or your Company is interested in raising its profile at “**Making Sense of Sensors**” via our Sponsorship opportunities. In addition to recognition of our sponsors at the start of the Conference, sponsorship provides a free advert in the event handbook, logo on all promotional material and online with weblink.

Please contact the IMAPS Secretariat for further details.

